

SN54LS597, SN54LS598, SN74LS597, SN74LS598 8-BIT SHIFT REGISTERS WITH INPUT LATCHES

SDLS007

D2635, JANUARY 1981 — REVISED MARCH 1988

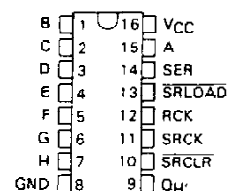
- 8-Bit Parallel Storage Register Inputs ('LS597)
- Parallel 3-State I/O, Storage Register Inputs, Shift Register Outputs ('LS598)
- Shift Register has Direct Overriding Load and Clear
- Accurate Shift-Frequency . . . DC to 20 MHz

description

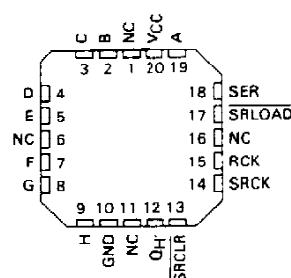
The 'LS597 comes in a 16-pin package and consists of an 8-bit storage latch feeding a parallel-in, serial-out 8-bit shift register. Both the storage register and shift register have positive-edge triggered clocks. The shift register also has direct load (from storage) and clear inputs.

The 'LS598 comes in a 20-pin package and has all the features of the 'LS597 plus 3-state I/O ports that provide parallel shift register outputs and also has multiplexed serial data inputs.

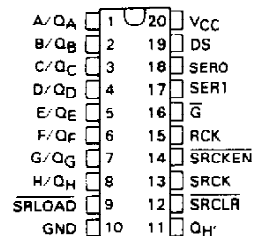
SN54LS597 . . . J OR W PACKAGE
SN74LS597 . . . N PACKAGE
(TOP VIEW)



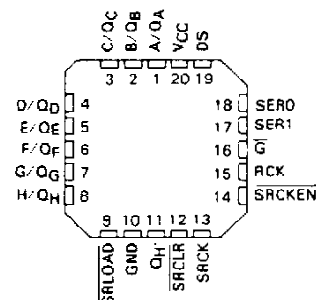
SN54LS597 . . . FK PACKAGE
(TOP VIEW)



SN54LS598 . . . J OR W PACKAGE
LS598 . . . DW OR N PACKAGE
(TOP VIEW)



SN54LS598 . . . FK PACKAGE
(TOP VIEW)



NC - No internal connection

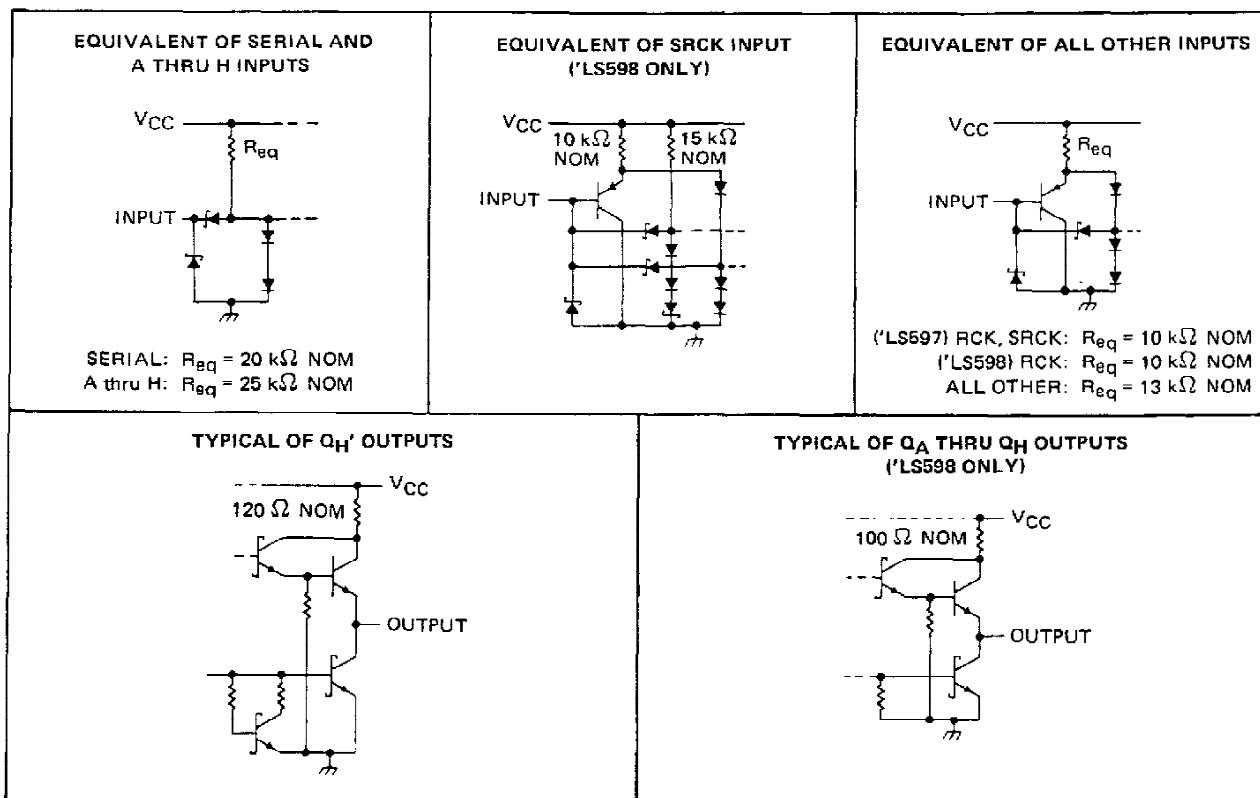
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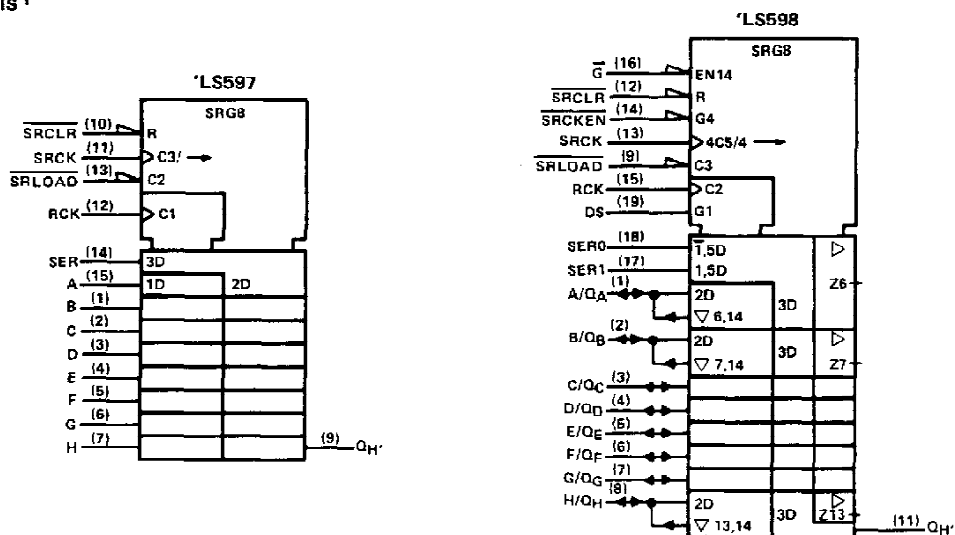
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SN54LS597, SN54LS598, SN74LS597, SN74LS598 **8-BIT SHIFT REGISTERS WITH INPUT LATCHES**

schematics of inputs and outputs



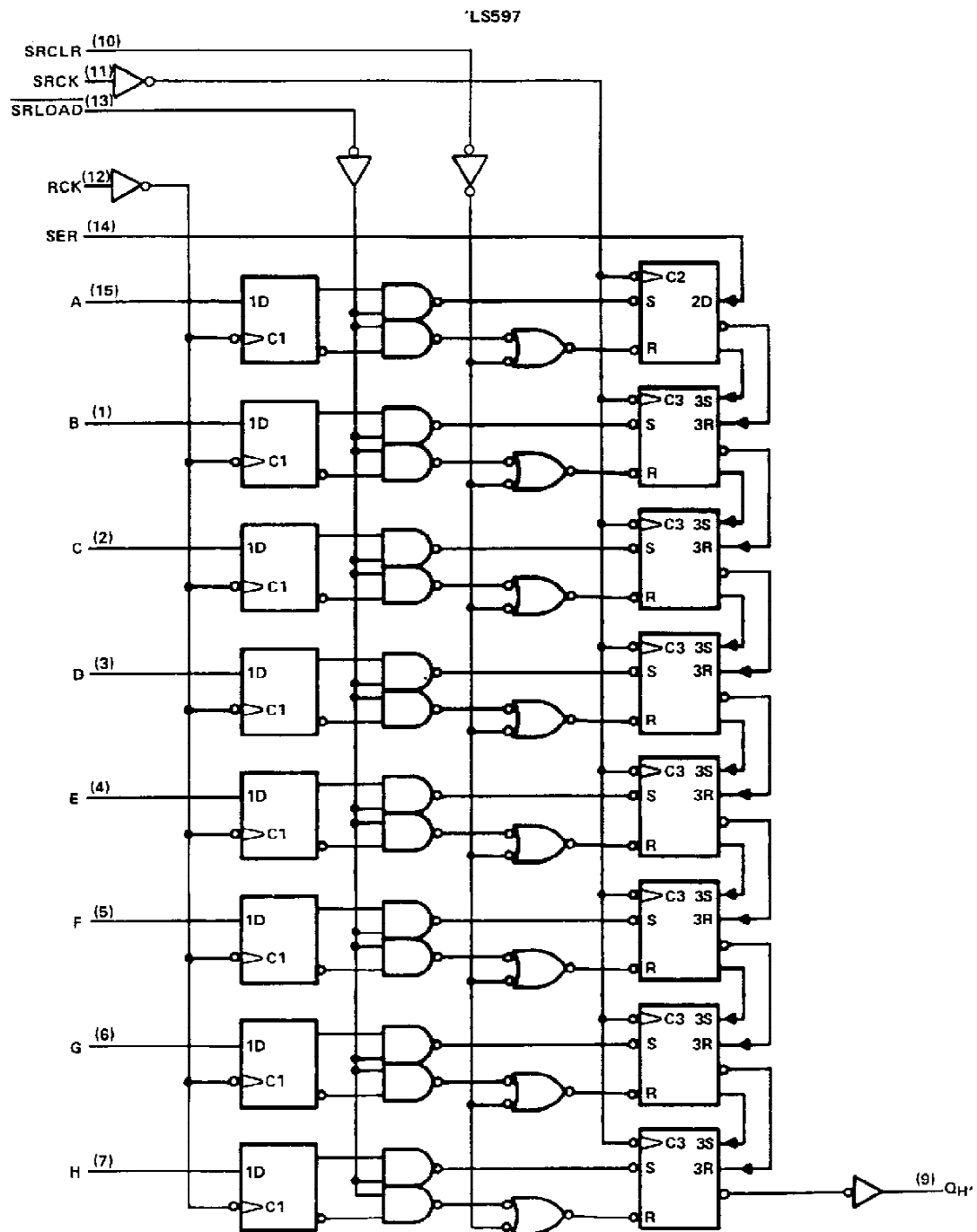
logic symbols†



†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.
Pin numbers shown are for DW, J, N, and W packages.

SN54LS597, SN74LS597
8-BIT SHIFT REGISTERS WITH INPUT LATCHES

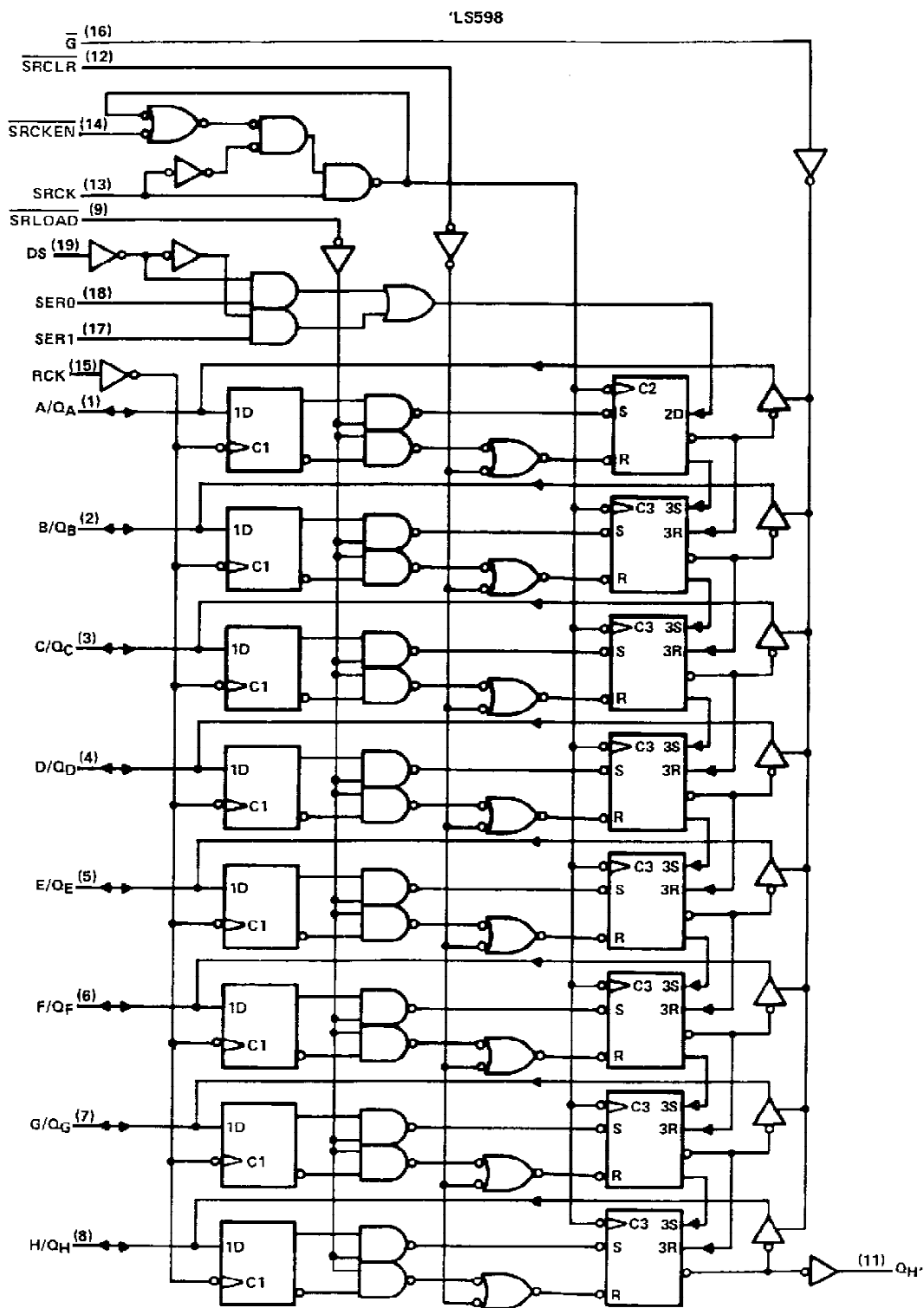
logic diagram (positive logic)



Pin numbers shown are for DW, J, N, and W packages.

SN54LS598, SN74LS598 **8-BIT SHIFT REGISTERS WITH INPUT LATCHES**

logic diagram (positive logic)



Pin numbers shown are for DW, J, N, and W packages.

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SN54LS597, SN54LS598, SN74LS597, SN74LS598

8-BIT SHIFT REGISTERS WITH INPUT LATCHES

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage (excluding I/O ports)	7 V
Off-state output voltage (including I/O ports)	5.5 V
Operating free-air temperature range: SN54LS597, SN54LS598	– 55°C to 125°C
SN74LS597, SN74LS598	0°C to 70°C
Storage temperature range	– 65°C to 150°C

NOTE 1: Voltage values are with respect to the network ground terminal.

recommended operating conditions

		SN54LS'			SN74LS'			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
I_{OH}	High-level output current	Q_H'		– 1	Q_H'		– 1	mA
		Q_A thru Q_H , 'LS598 only		– 1	Q_A thru Q_H , 'LS598 only		– 2.6	
I_{OL}	Low-level output current	Q_H'		8	Q_H'		16	mA
		Q_A thru Q_H , 'LS598 only		12	Q_A thru Q_H , 'LS598 only		24	
f_{SCK}	Shift clock frequency	0		20	0		20	MHz
t_w	Pulse duration	SRCK	high	15			15	ns
			low	35			35	
		RCK		20			20	
		SRCLR		20			20	
t_{su}	Setup time	SRLOAD		40			40	ns
		Data before RCK ↑		20			20	
		DS before SRCK ↑ ('LS598 only)		30			30	
		SRCKEN low before SRCK ↑ ('LS598 only)		20			20	
		SRCLR inactive before SRCK ↑		25			25	
		SRLOAD inactive before SRCK ↑		30			30	
t_h	Hold time	RCK ↑ before SRLOAD ↑ (see Note 2)		40			40	ns
		SER before SRCK ↑		20			20	
T_A	Operating free-air temperature	– 55		125	0		70	°C

NOTE 2: The RCK ↑ before SRLOAD ↑ setup time ensures the data saved by RCK ↑ will also be loaded into the shift register.

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SN54LS597, SN54LS598, SN74LS597, SN74LS598 **8-BIT SHIFT REGISTERS WITH INPUT LATCHES**

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†			SN54LS'		SN74LS'		UNIT			
						MIN	TYP‡	MAX	MIN		TYP‡	MAX	
VIK			VCC = MIN, I1 = - 18 mA			- 1.5		- 1.5		V			
VOH	'LS598 Q	VCC = MIN, VIH = 2 V, VIL = MAX	IOH = - 1 mA		2.4	3.2			2.4	3.1	V		
	IOH = - 2.6 mA												
	QH'		IOH = - 1 mA		2.4	3.2			2.4	3.2			
VOL	'LS598 Q	VCC = MIN, VIH = 2 V, VIL = MAX	IOL = 12 mA		0.25		0.4		0.25		0.4		V
	IOL = 24 mA						0.35		0.5				
	IOL = 8 mA		0.25		0.4		0.25		0.4				
	IOL = 16 mA						0.35		0.5				
IOZH	'LS598 Q	VCC = MAX, VIH = 2 V, VIL = MAX, VO = 2.7 V				20				20		µA	
IOZL	'LS598 Q	VCC = MAX, VIH = 2 V, VIL = MAX, VO = 0.4 V				- 0.4				- 0.4		mA	
II	'LS598 Q	VCC = MAX		VI = 5.5 V		0.1				0.1		mA	
	Others			VI = 7 V		0.1				0.1			
IIH		VCC = MAX, VI = 2.7 V				20				20		µA	
IIL	'LS598 SRCK	VCC = MAX, VI = 0.4 V				- 0.8				- 0.8		mA	
	SER. A Thru H			- 0.4		- 0.4							
	Others			- 0.2		- 0.2							
IOS§	'LS598 Q	VCC = MAX, VO = 0 V		- 30		- 130		- 30		- 130		mA	
	QH'			- 20		- 100		- 20		- 100			
ICC	'LS597	I CCH	VCC = MAX, All possible inputs grounded, All outputs open		35		53		35		53		mA
		ICCL			35		53		35		53		
	'LS598	I CCH			45		68		45		68		
		ICCL			54		80		54		80		
		ICCZ			56		85		56		85		

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$

§ Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.

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SN54LS597, SN54LS598, SN74LS597, SN74LS598
8-BIT SHIFT REGISTERS WITH INPUT LATCHES

switching characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$. (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	LS597			LS598			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
f_{max}	SRCK	Q	$R_L = 667\ \Omega$, $C_L = 45\text{ pF}$	20	35		20	35		MHz
f_{max}	SRCK	Q_H'	$R_L = 1\text{ k}\Omega$, $C_L = 30\text{ pF}$	20	35					MHz
t_{PLH}	SRCK↑	Q_H'	$R_L = 1\text{ k}\Omega$, $C_L = 30\text{ pF}$		15	23		11	17	ns
t_{PHL}	SPCK↑	Q_H'			20	30		15	23	ns
t_{PLH}	SRLOAD↓	Q_H'			38	57		28	42	ns
t_{PHL}	SRLOAD↓	Q_H'			29	44		20	30	ns
t_{PHL}	SRCLR↓	Q_H'			24	36		18	27	ns
t_{PLH}	RCK↑	Q_H'	$R_L = 1\text{ k}\Omega$, $C_L = 30\text{ pF}$ SRLOAD = L		41	60		32	48	ns
t_{PHL}	RCK↑	Q_H'			32	48		24	36	ns
t_{PLH}	SRCK↑	Q	$R_L = 667\ \Omega$, $C_L = 45\text{ pF}$					12	18	ns
t_{PHL}	SRCK↑	Q						19	28	ns
t_{PLH}	SRLOAD↓	Q						32	48	ns
t_{PHL}	SRLOAD↓	Q						27	40	ns
t_{PHL}	SRCLR↓	Q						25	38	ns
t_{PZH}	G↓	Q						26	31	ns
t_{PZL}	G↓	Q						29	43	ns
t_{PHZ}	G↑	Q	$R_L = 667\ \Omega$, $C_L = 5\text{ pF}$					25	38	ns
t_{PLZ}	G↑	Q						20	30	ns

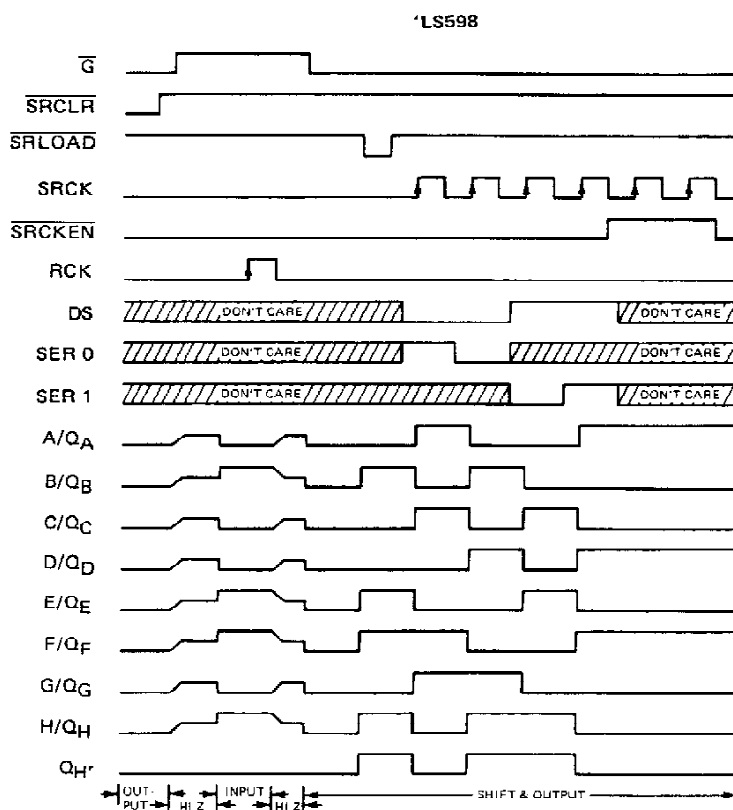
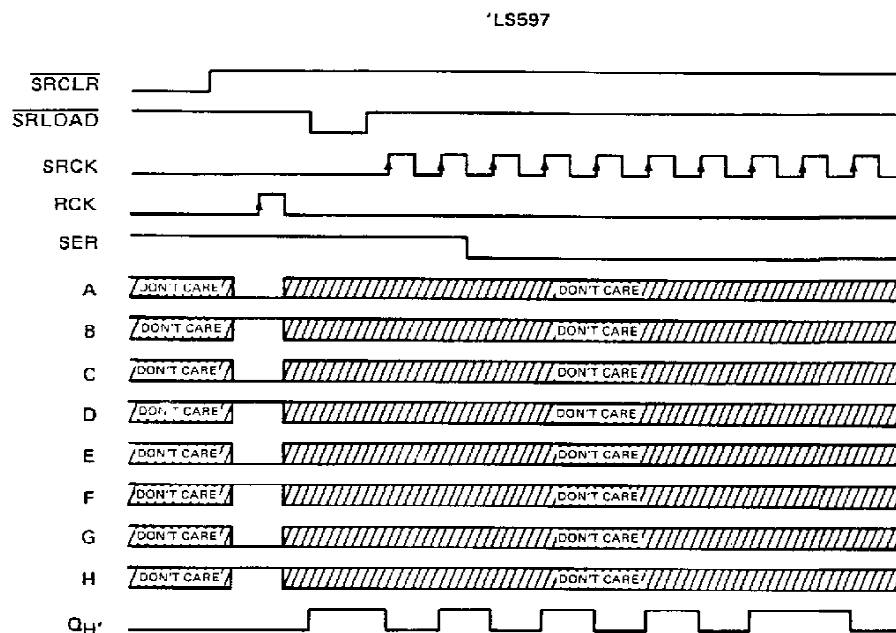
NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

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SN54LS597, SN54LS598, SN74LS597, SN74LS598 **8-BIT SHIFT REGISTERS WITH INPUT LATCHES**

typical operating sequences




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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-89444012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8944401EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
5962-8944401EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
5962-8944401FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
5962-8944401FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
5962-89756012A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
5962-89756012A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
5962-8975601SA	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI
5962-8975601SA	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI
SN54LS597J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SN54LS597J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SN54LS598J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI
SN54LS598J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI
SN74LS597D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS597N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS597NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS597NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS597NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS598N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LS598N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS598NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS598NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54LS597FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS597FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS597J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS597J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS597W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS597W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS598FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54LS598FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54LS598J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI
SNJ54LS598J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI
SNJ54LS598W	OBSOLETE			20		TBD	Call TI	Call TI
SNJ54LS598W	OBSOLETE			20		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS597NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS597NSR	SO	NS	16	2000	346.0	346.0	33.0

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

W (R-GDFP-F16)

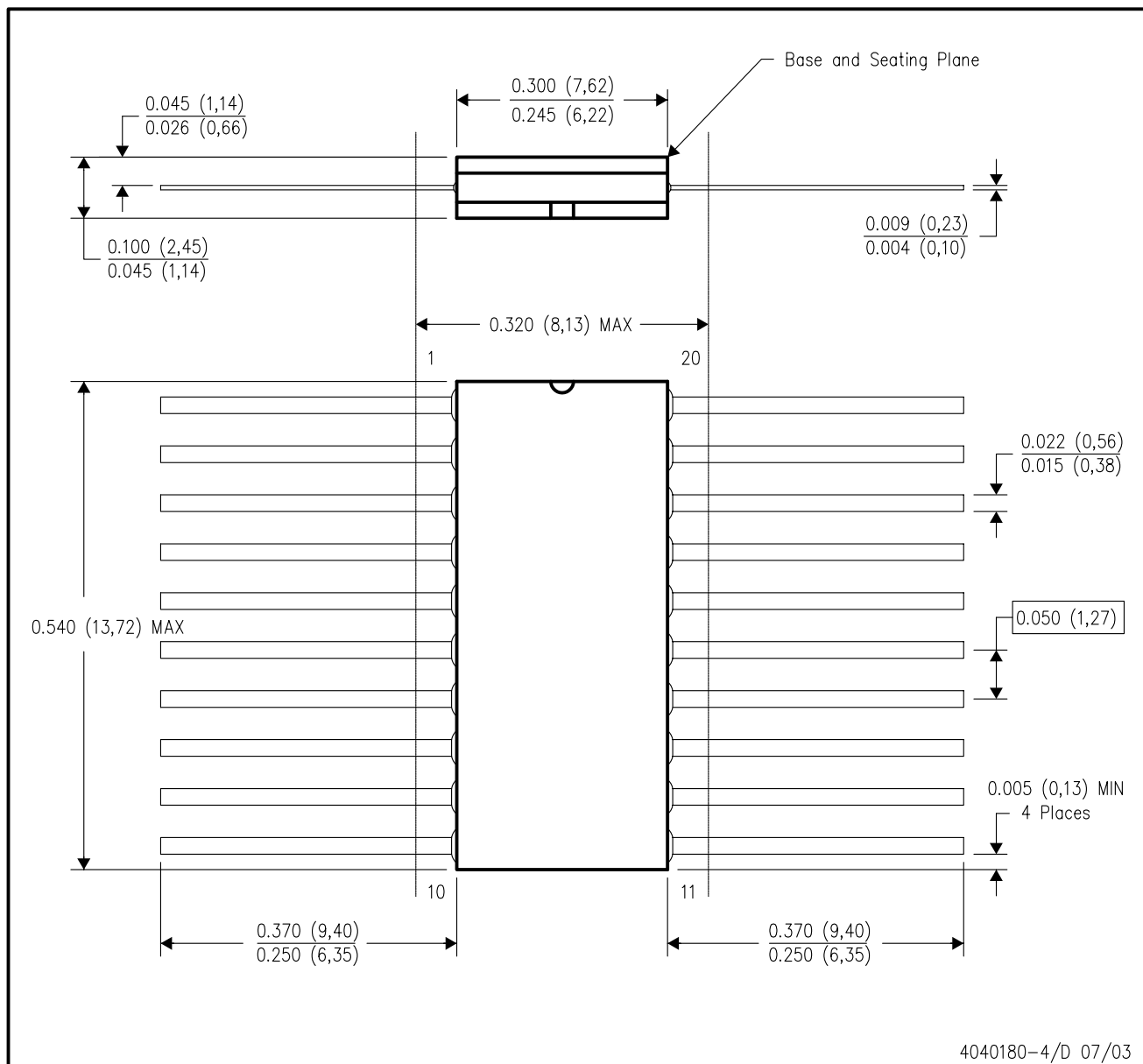
CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

W (R-GDFP-F20)

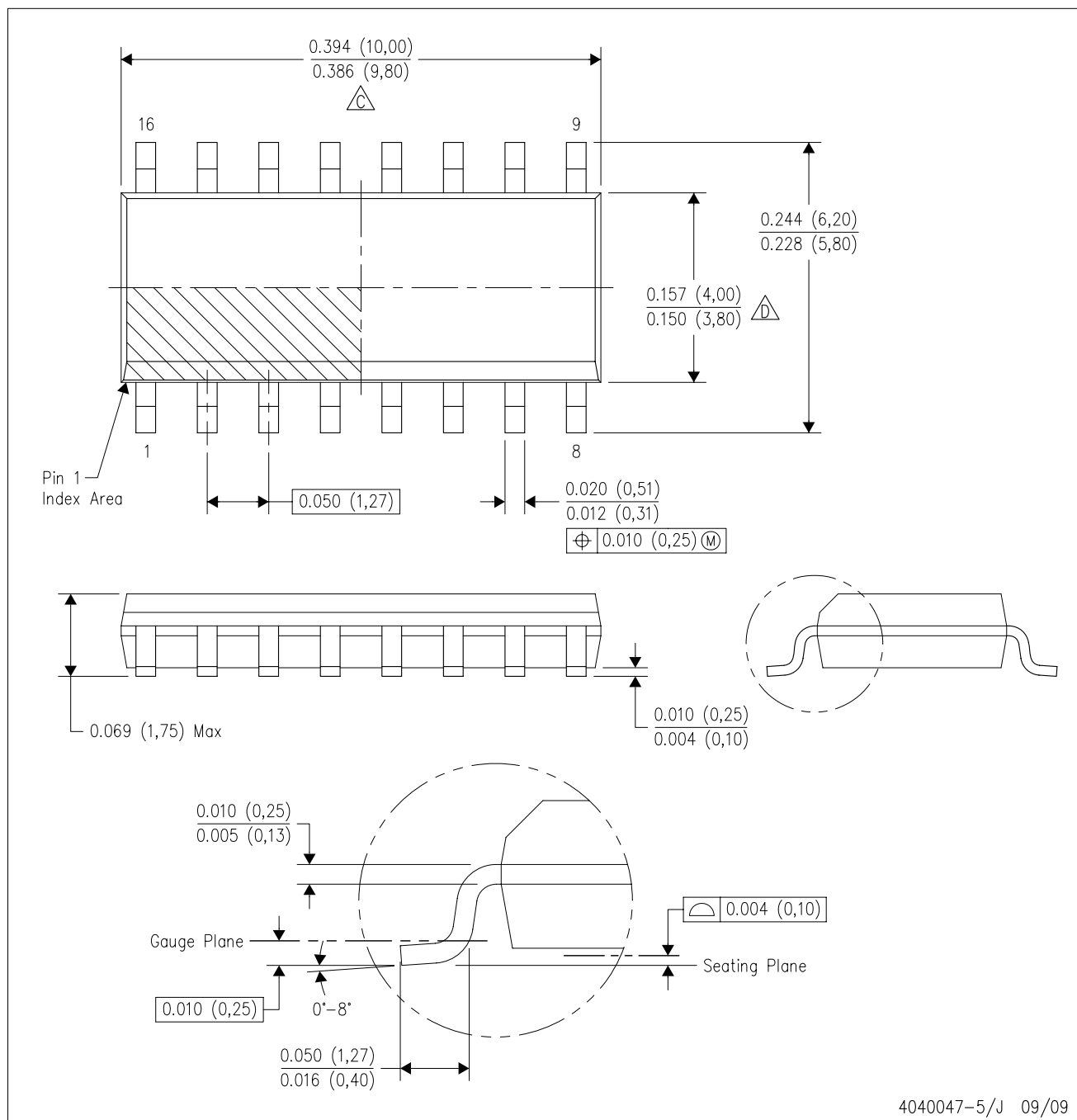
CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within Mil-Std 1835 GDFP2-F20

D (R-PDSO-G16)

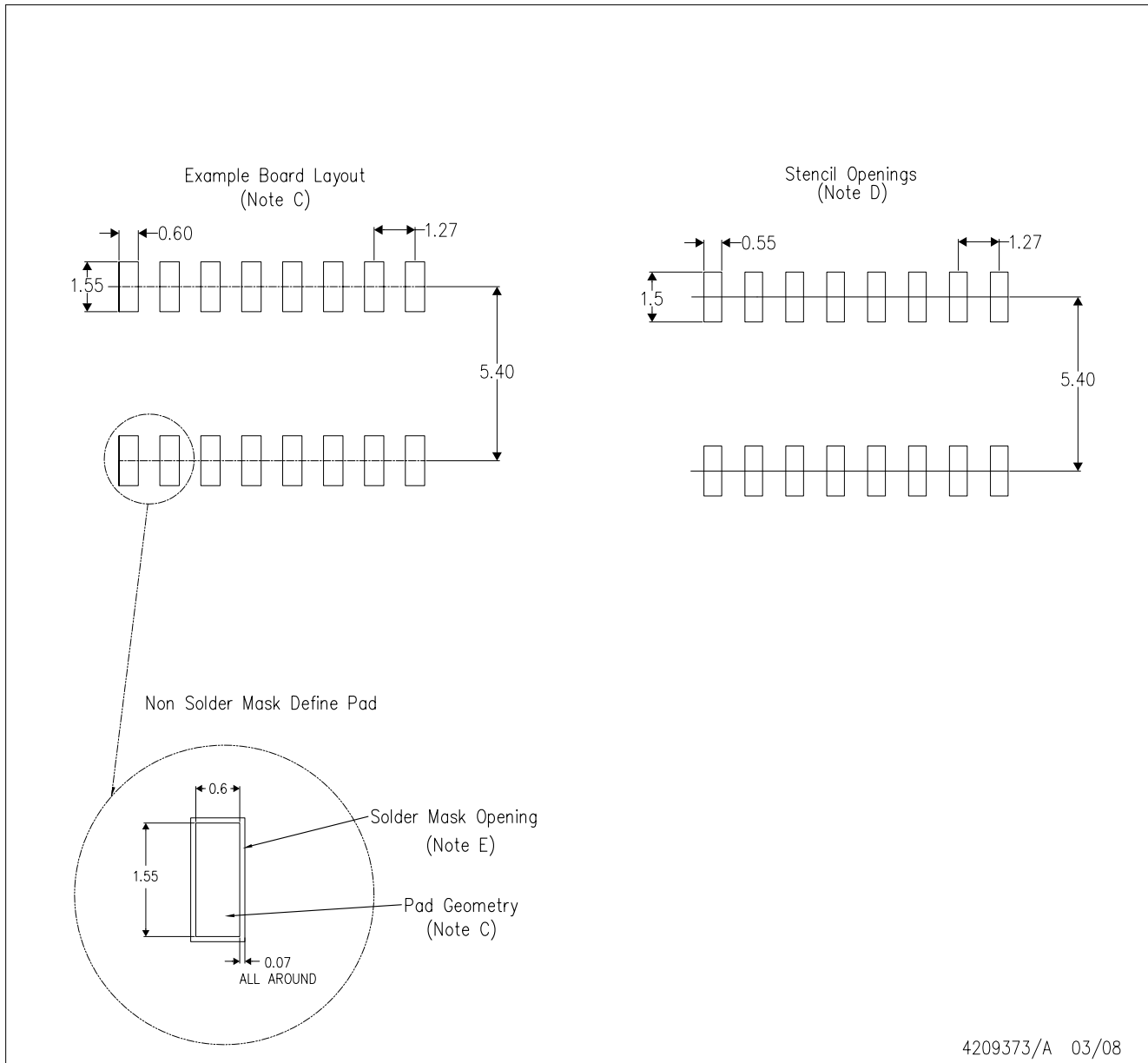
PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.

D(R-PDSO-G16)



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

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